



Properties of Mesoscopic-Scale Thick Ferromagnetic Thin Films

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Message from the Guest Editor

Ferromagnetic thin films are currently used in the device systems of many application fields. The film's morphology is induced by its growth process, which simultaneously impacts its inseparable bulk and surface parts. From a practical viewpoint, the bulk and surface parts correspond to the film's thickness and surface roughness (rms), respectively, which are differently impacted by a constant magnetic field effect due to their specific individual microstructures. All of the resulting film's magnetic properties are then a combined contribution of these two sample characteristics. By and large, the evolution of their global characteristics, such as coercivity or squareness, is most of the time investigated with respect to thickness only. Local properties, like magnetic domain size or domain wall thickness, are also examined through the same characteristic. Such a property evolution approach is restrictive as it does not cover the entire range of real-world thin films. Investigations of particular interest could be expected for that purpose.





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Message from the Editor-in-Chief

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